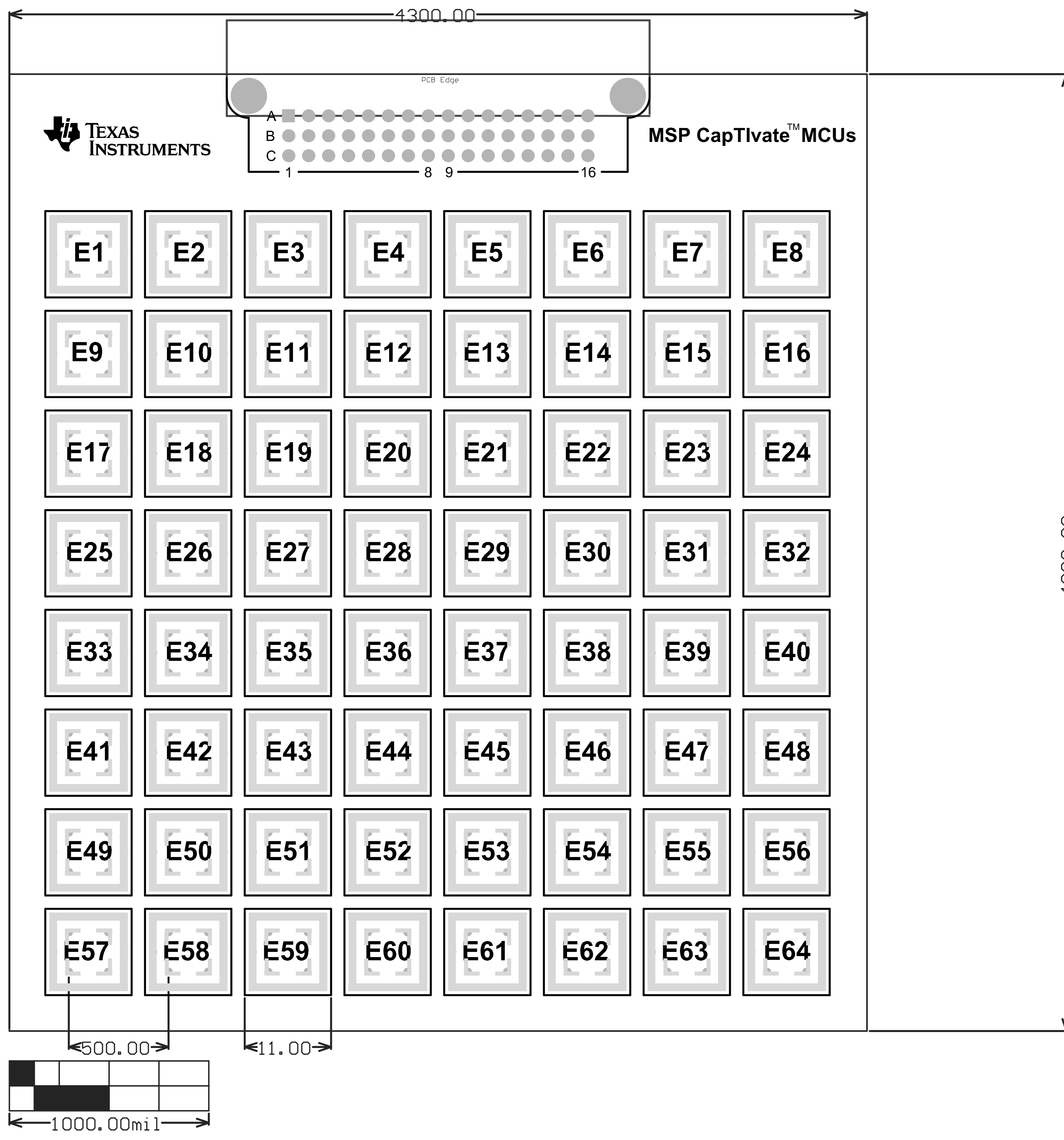


Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	59.20mil	4.8	
5	Bottom Layer	Copper	1.40mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				



DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
 MIN. CLEARANCE: 0.2 mm
 MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
 FR-408 FR-4 High Tg OTHER _____
 THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

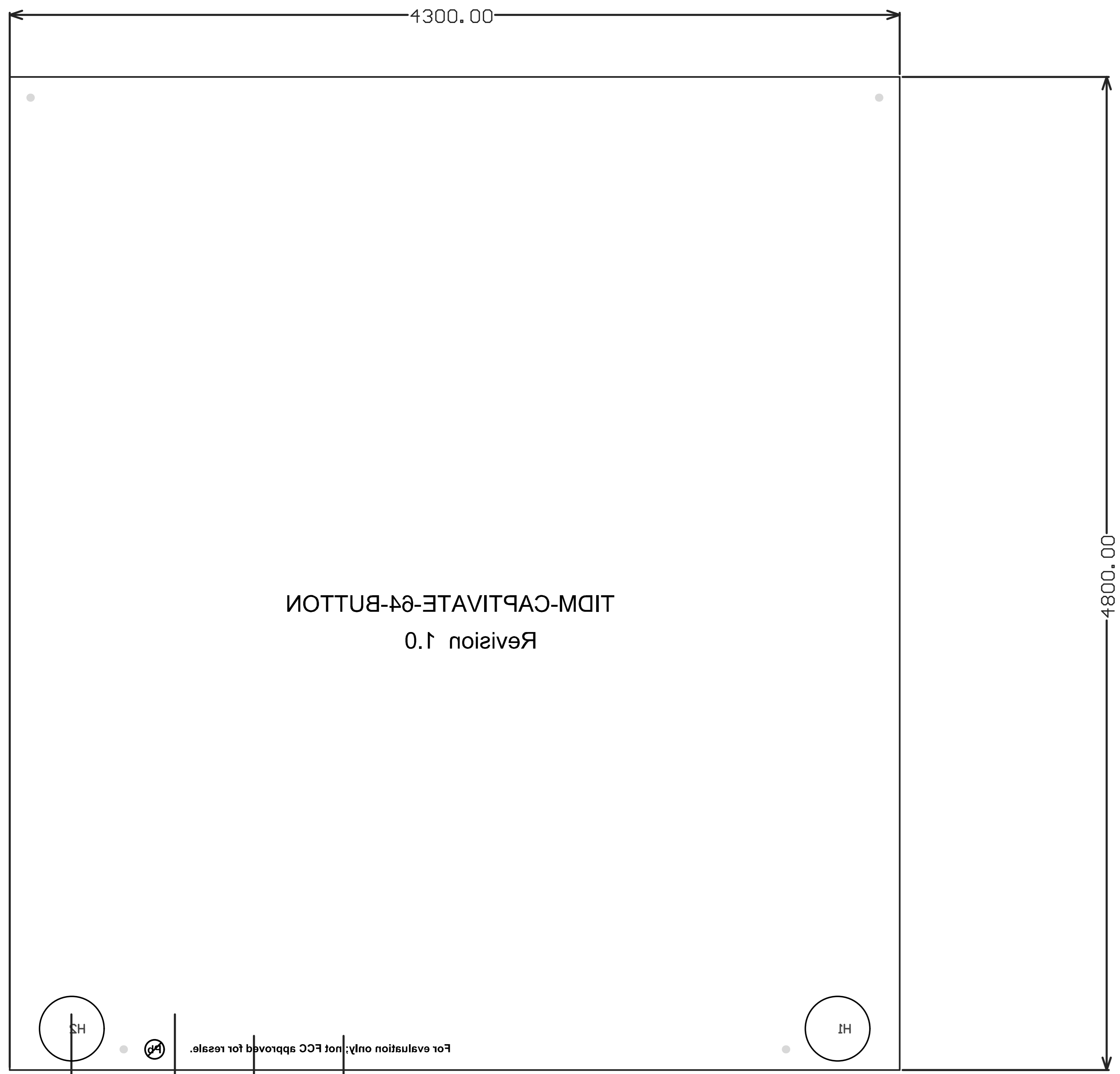
DRILLING:
 REFERENCE: AS SHOWN NC_DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR:
 GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENIG) ENEPIG

FILE NAME: TIDM-CAPTIVATE-64-BUTTON_PCB.PcbDoc	
ENGINEER: W. Schnoor	LAYOUT BY: W. Schnoor
SCALE: 1.00	ALTUM DESIGNER VERSION: 14.3.18.45973

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	59.20mil	4.8	
5	Bottom Layer	Copper	1.40mil		
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 OTHER +/- _____

DRILLING:
 REFERENCE: AS SHOWN NC_DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR:
 GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENIG) ENEPIG

FILE NAME: TIDM-CAPTIVATE-64-BUTTON_PCB.PcbDoc	
ENGINEER: W. Schnoor	LAYOUT BY: W. Schnoor
SCALE: 1.00	ALTIUM DESIGNER VERSION: 14.3.18.45973

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